



MUSB, MUSBR, UUSB SERIES

MINI & MICRO USB 2.0 INTERFACES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MUSB or www.samtec.com?MUSBR

- Insulator Material:** High Temperature Thermoplastic
- Contact Material:** Phosphor Bronze
- Shell Material:** Brass
- Plating:** Gold on Mating Area, Nickel on Shell, Tin on Tails
- Operating Temp Range:** -50°C to +85°C
- Current Rating:** 1A per contact
- Voltage Rating:** 30 VRMS
- Contact Resistance:** 50 mΩ max
- Minimum Cycles:** 1500
- Packaging:** Packaged and shipped in Bulk Packaging Trays; Trays suitable for automation are available upon request.
- RoHS Compliant:** Yes
- Lead-Free Solderable:** Yes

TYPE	NO. OF CONTACTS	PLATING	COLOR	TYPE	SM	A
MUSB = Mini USB 2.0	-05	-F = Gold Flash on Mating Area, Tin on Tails	-O = Orange	-B = B Type (MUSB & MUSBR)		
MUSBR = High Retention Mini USB 2.0		-S = 30μ" (0,76μm) Gold on Mating Area, Tin on Tails		-AB = AB Type (MUSB only)		
				-A = A Type (MUSBR only)		

ALSO AVAILABLE
Mini USB-A Type. Call Samtec.

RUGGEDIZED by SAMTEC
• High retention option

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?UUSB

- Insulator Material:** Black LCP
- Contact Material:** Phosphor Copper
- Plating:** Au over 50μ" (1,27μm) Ni
- Shield Plating:** Sn over 50μ" (1,27μm) Ni
- Operating Temp Range:** -30°C to +80°C
- Current Rating:** 1A (pin 2, 3, 4) per signal contact, 1.8A (pin 1, 5) per power contact
- Voltage Rating:** 100 VAC
- Contact Resistance:** 50 mΩ max
- Cycles:** 10,000
- RoHS Compliant:** Yes

UUSB	TYPE	S	PLATING	TERMINATION	TR
UUSB = Micro USB 2.0	-AB = Micro AB		-F = Gold Flash on Mating Area and Tails	-SM = Surface Mount	-TR = Tape & Reel
	-B = Micro B		-S = 30μ" (0,76 μm) Gold on Mating Area, Gold Flash on Tails		

PRELIMINARY

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM